

TABLE OF MATERIAL DECLARATION

This table is used for part such as: Leadframe, Die attach material, Gold Wire, Solder, Mold Compound, Coating Material, Marking Ink.

ASSEMBLY SITE : Unisem Chengdu
PACKAGE : 4L STSLP IXILeadfree / Green Compound
CUSTOMER : SGM
Device: SGM2036-3.0AYUDH4G
Compile Date: 2015/3/3

No.	Part Name	Material Name	Component Wt ^(D) (mg)	Material Content (Element)	CAS Number	Element Wt ^(A) (%)	Element Wt (mg)	Wt % Of Total Unit Wt	ppm
1	Leadframe	4L STSLP1X1	1.3023	Cu	7440-50-8	97.52	1.2700	58.3521	583521
				Fe	7439-89-6	2.30	0.0300	1.3762	13762
				P	7723-14-0	0.03	0.0004	0.0180	180
				Zn	7440-66-6	0.15	0.0020	0.0898	898
		NiPdAu	0.0091	Au	7440-57-5	0.66	0.00006	0.0028	28
				Ni	7786-81-4	0.70	0.000064	0.0029	29
				Pd	7440/5/3	98.64	0.00898	0.4126	4126
2	Die attach material	84-3J	0.0200	Silica, crystalline	14808-60-7	42.50	0.0085	0.3912	3912
				Epoxy resin	TS ref# 10030	25.00	0.0050	0.2301	2301
				Epoxy resin	TS ref# 10114	15.00	0.0030	0.1381	1381
				Epoxy resin modifier	TS ref# 10038	15.00	0.0030	0.1381	1381
				Amine	TS ref# 10039	2.50	0.0005	0.0230	230
3	Gold Wire	0.8MIL GFD	0.0157	Au	7440-57-5	100.00	0.0157	0.7193	7193
4	Mold Compound	EME G770HP green compound	0.6780	Epoxy Resin A	Trade secret	3	0.0203	0.9345	9345
				Epoxy Resin B	Trade secret	1	0.0068	0.3115	3115
				Phenol Resin	Trade secret	2	0.0136	0.6230	6230
				Carbon Black	1333-86-4	0.3	0.0020	0.0935	935
				Silica Fused	60676-86-0	93.7	0.6353	29.1882	291882
5	Die	Silicon chip	0.1514	Silicon	7440-21-3	100.00	0.1514	6.9552	69552
Total unit weight =			2.176						
							2.176	100.0000	1000000

Note:

- (A)** Element Wt Composition is derived from MSDS and/or material C of C from Vendors
(B) Wt of silver spotted on leadframe is estimated.
(C) Element Wt Composition of Pb is derived from raw material C of C from Vendors
(D) Component Weight based on assembly of generic parts.